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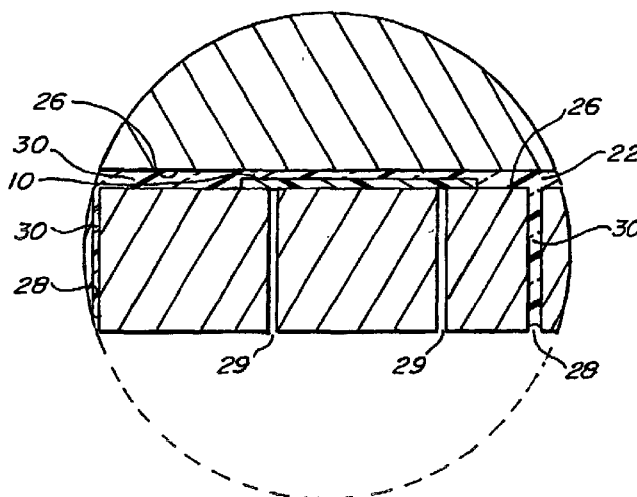
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(54) Title: SEMICONDUCTOR COMPONENT HANDLING DEVICE HAVING AN ELECTROSTATIC DISSIPATING FILM



(57) Abstract: A system and method for including a thin conductive polymer film (10), such as carbon-filled PEEK, in the molding process for handlers (34), transporters, carriers, trays (36) and like devices utilized in the semiconductor processing industry. The conductive film (10) of predetermined size and shape is selectively placed along a shaping surface (26) in a mold cavity (22) for alignment with a desired target surface of a moldable material (30). The molding process causes a surface of the film (10) to bond to a contact surface of the moldable material (30) such that the film is permanently adhered to the moldable material. As a result, a compatible conductive polymer can be selectively bonded only to those target surfaces where electrostatic dissipation is needed.



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